



ESD SMD Comm COG, Ceramic, 0.047 uF, 2%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805, 0.7 mm



General Information	
Ceneral III of mation	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	14 mg
Shelf Life	78 Weeks
MSL	1

0.047 uF

21.2766 GOhms

0805
2mm +/-0.2mm
1.25mm +/-0.2mm
1.25mm +/-0.15mm
0.7mm MIN
0.5mm +/-0.25mm

nm +/-0.2mm	Measurement Condition	1 kHz 1.0Vrms
25mm +/-0.2mm	Tolerance	2%
25mm +/-0.15mm	Voltage DC	25 VDC
7mm MIN	ESD Level per AEC-Q200	25,000 V ESD Level
5mm +/-0.25mm	Dielectric Withstanding Voltage	62.5 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
ılk, Bag	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour

Insulation Resistance

Specifications
Capacitance

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

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